# Raise3D DF2 Technical Specifications

*The Raise3D DF2 solution is a Digital Light Printing (DLP) system offering speed, quality, exceptional reliability and efficient workflow via RFID. It is designed for engineering prototyping, manufacturing aids, and low-volume production using a wide variety of high-performance*

| Printer | Raise3D DF2 | |
|---|---|---|
| **Printer Hardware** | Print Technology | DLP |
| | Build Volume (W × D × H) | 200 × 112 × 300 mm (7.87 × 4.41 × 11.8 inch) |
| | XY Pixel Size | 78.5 micron |
| | XY Resolution | 2560 × 1440 |
| | Max Z Workload | 12 kg |
| | Layer Height | 50-100 micron |
| | Max Printing Speed | 25 mm/h (0.1 mm per layer) |
| | Resin Level Detection | Yes |
| | Auto Resin Refill | Yes |
| | Control Panel | Touch Screen (1920 × 720, Magic Layout) |
| | Level Calibration | Calibrated in Factory |
| | Chamber Heating | Yes (Max 40℃) |
| **Resins** (Available Options) | Raise3D Standard | White |
| | Raise3D High Detail | Apricot |
| | Raise3D Tough 2K | Grey |
| | Raise3D Rigid 3K | Grey |
| | Raise3D High Clear | Coming Soon |
| | Raise3D High Temperature | Coming Soon |
| | Open Resin Program | Coming Soon |
| **Software and Network** | Connectivity | Wi-Fi, LAN, USB port × 2, Live camera |
| | Network | Ethernet, Wireless 802.11 b/g/n |
| | Slicing Software | ideaMaker |
| | Remote Management Software | RaiseCloud |
| | Supported File Types | STL/ OBJ/ 3MF/ OLTP |
| | Supported OS | WINDOWS/ macOS/ LINUX |
| **Operation and Shipping** | Power Supply Input | 100-240VAC, 50/60 Hz 230V @ 3.3A |
| | Operating Ambient Temperature | 15 - 30°C, 10 - 90% RH Non-Condensing (HOLD) |
| | Storage Temperature | -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD) |
| | Machine Size (W × D × H) | 450 × 400 × 730 mm (17.7 × 15.7 × 28.7 inch) |
| | Weight | 40 kg (Net Weight) |
| | | 59.4 kg (Gross Weight) |
| | Shipping Dimensions | 710 × 595 × 980 mm (28.0 × 23.4 × 38.6 inch) |

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# Raise3D DF Wash & DF Cure Technical Specifications

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| Machine | Raise3D DF Wash |
|---|---|
| **Hardware** | Washing Tank Volume   14 L |
| | Max Washing Volume   200 × 112 × 300 mm (7.87 × 4.41 × 11.8 inch) |
| | Compatible Solvent   IPA, Water, TPM |
| | RFID Print Platform   Supported |
| | Automated Waste Drainage   Yes |
| **Operation and Shipping** | Power Supply Input   100-240VAC, 50/60 Hz, 0.55 A/230VAC |
| | Operating Ambient Temperature   10°C-35°C |
| | Storage Temperature   -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD) |
| | Machine Gross Weight   45.4 kg |
| | Grey Tank Gross Weight   0.65 kg |
| | Machine Size (W × D × H)   400 × 410 × 646 mm (15.7 × 16.1 × 25.4 inch) |
| | Machine Shipping Dimension   725 × 585 × 915 mm (28.5 × 23.0 × 36.0 inch) |
| | Grey Tank Shipping Dimension   407 × 247 × 349 mm (16.0 × 9.7 × 13.7 inch) |

| Machine | Raise3D DF Cure |
|---|---|
| **Hardware** | Max Curing Size   φ 230 x 300 mm (φ 9 x 11.8 inch) |
| | Curing Source   LED (365nm, 385nm, 405nm Mixed) |
| | Air Heating (Max Temperature 120°C) |
| **Operation and Shipping** | Power Supply Input   100-240 V AC, 50/60 Hz, 230 V AC @ 2.6 A |
| | Operating Ambient Temperature   10-35°C |
| | Storage Temperature   -25 to 55°C, 10 - 90% RH Non-Condensing (HOLD) |
| | Net Weight   31.95 kg |
| | Gross Weight   45.5 kg |
| | Machine Size (W × D × H)   490 × 400 × 610 mm (19.3 × 15.7 × 24.0 inch) |
| | Shipping Dimension (W × D × H)   725 × 585 × 850 mm (28.5 × 23.0 × 33.5 inch) |

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